

## Product Summary

RoHS

- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Super Low Gate Charge
- ★ Advanced Trench MOS Technology

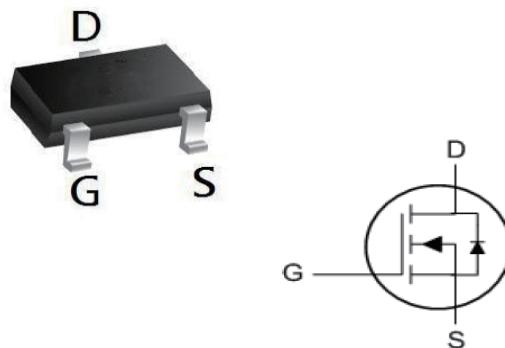
| BVDSS | RDSON | ID |
|-------|-------|----|
| 40V   | 30mΩ  | 5A |

## Applications

The 2318 is the high cell density trenched N ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The 2318 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

## SOT 23 Pin Configurations



## Absolute Maximum Ratings

| Symbol                            | Parameter                                 |                        | Max.       | Units |
|-----------------------------------|---|------------------------|------------|-------|
| V <sub>DSS</sub>                  | Drain-Source Voltage                      |                        | 40         | V     |
| V <sub>GSS</sub>                  | Gate-Source Voltage                       |                        | ±20        | V     |
| I <sub>D</sub>                    | Continuous Drain Current                  | T <sub>C</sub> = 25°C  | 5          | A     |
|                                   |   | T <sub>C</sub> = 100°C | 3          | A     |
| I <sub>DM</sub>                   | Pulsed Drain Current <small>note1</small> |                        | 20         | A     |
| P <sub>D</sub>                    | Power Dissipation                         | T <sub>C</sub> = 25°C  | 1.6        | W     |
| R <sub>θJA</sub>                  | Thermal Resistance, Junction to Ambient   |                        | 78         | °C/W  |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Temperature Range   |                        | -55 to 150 | °C    |

## Thermal Data

| Symbol           | Parameter   | Typ. | Max. | Unit |
|------------------|---|------|------|------|
| R <sub>θJA</sub> | Thermal Resistance Junction-ambient (Steady State) <sub>1</sub> | ---  | 60   | °C/W |
| R <sub>θJC</sub> | Thermal Resistance Junction-Case <sub>1</sub>                   | ---  | 3.2  | °C/W |

Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

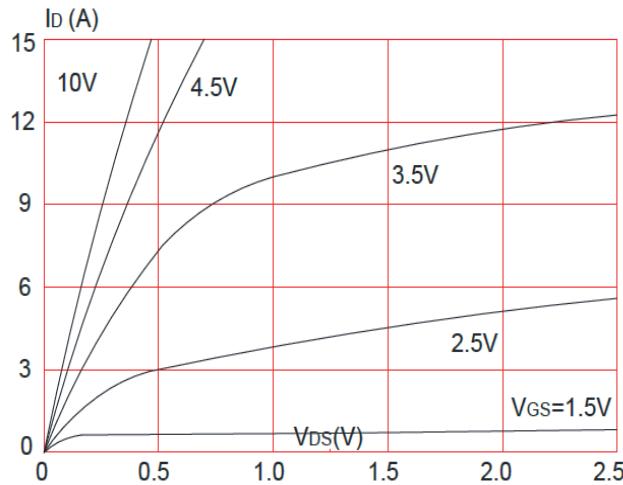
| Symbol  | Parameter  | Test Condition  | Min. | Typ. | Max.      | Units            |
|---|--|---|------|------|-----------|------------------|
| <b>Off Characteristics</b>                                    |  |   |      |      |           |                  |
| $V_{(BR)DSS}$   | Drain-Source Breakdown Voltage                           | $V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$   | 40   | -    | -         | V                |
| $I_{DSS}$   | Zero Gate Voltage Drain Current                          | $V_{DS}=40\text{V}$ , $V_{GS}=0\text{V}$ ,  | -    | -    | 1         | $\mu\text{A}$    |
| $I_{GSS}$   | Gate to Body Leakage Current                             | $V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$  | -    | -    | $\pm 100$ | $\text{nA}$      |
| <b>On Characteristics</b>                                     |  |   |      |      |           |                  |
| $V_{GS(\text{th})}$   | Gate Threshold Voltage                                   | $V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$  | 1    | 1.5  | 2.2       | V                |
| $R_{DS(on)}$<br><small>note3</small>                          | Static Drain-Source on-Resistance                        | $V_{GS}=10\text{V}$ , $I_D=4\text{A}$   | -    | 30   | 40        | $\text{m}\Omega$ |
|   |  | $V_{GS}=4.5\text{V}$ , $I_D=3\text{A}$  | -    | 40   | 60        |                  |
| <b>Dynamic Characteristics</b>                                |  |   |      |      |           |                  |
| $C_{iss}$   | Input Capacitance  | $V_{DS}=20\text{V}$ , $V_{GS}=0\text{V}$ ,<br>$f=1.0\text{MHz}$                                       | -    | 435  | -         | pF               |
| $C_{oss}$   | Output Capacitance                                       |   | -    | 58   | -         | pF               |
| $C_{rss}$   | Reverse Transfer Capacitance                             |   | -    | 35   | -         | pF               |
| $Q_g$   | Total Gate Charge  | $V_{DS}=20\text{V}$ , $I_D=3\text{A}$ ,<br>$V_{GS}=10\text{V}$  | -    | 11   | -         | nC               |
| $Q_{gs}$  | Gate-Source Charge                                       |   | -    | 2    | -         | nC               |
| $Q_{gd}$  | Gate-Drain("Miller") Charge                              |   | -    | 2.5  | -         | nC               |
| <b>Switching Characteristics</b>                              |  |   |      |      |           |                  |
| $t_{d(on)}$   | Turn-on Delay Time                                       | $V_{DD}=20\text{V}$ , $I_D=4\text{A}$ ,<br>$R_L=1\Omega$ , $R_{GEN}=3\Omega$ ,<br>$V_{GS}=10\text{V}$ | -    | 10   | -         | ns               |
| $t_r$   | Turn-on Rise Time  |   | -    | 8    | -         | ns               |
| $t_{d(off)}$  | Turn-off Delay Time                                      |   | -    | 29   | -         | ns               |
| $t_f$   | Turn-off Fall Time                                       |   | -    | 12   | -         | ns               |
| <b>Drain-Source Diode Characteristics and Maximum Ratings</b> |  |   |      |      |           |                  |
| $I_S$   | Maximum Continuous Drain to Source Diode Forward Current | -   | -    | 5    | -         | A                |
| $I_{SM}$  | Maximum Pulsed Drain to Source Diode Forward Current     | -   | -    | 20   | -         | A                |
| $V_{SD}$  | Drain to Source Diode Forward Voltage                    | $V_{GS}=0\text{V}$ , $I_S=5\text{A}$  | -    | -    | 1.2       | V                |
| $t_{rr}$  | Body Diode Reverse Recovery Time                         | $T_J=25^\circ\text{C}$ ,  | -    | 20   | -         | ns               |
| $Q_{rr}$  | Body Diode Reverse Recovery Charge                       | $I_F=5\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$   | -    | 11   | -         | nC               |

Notes:

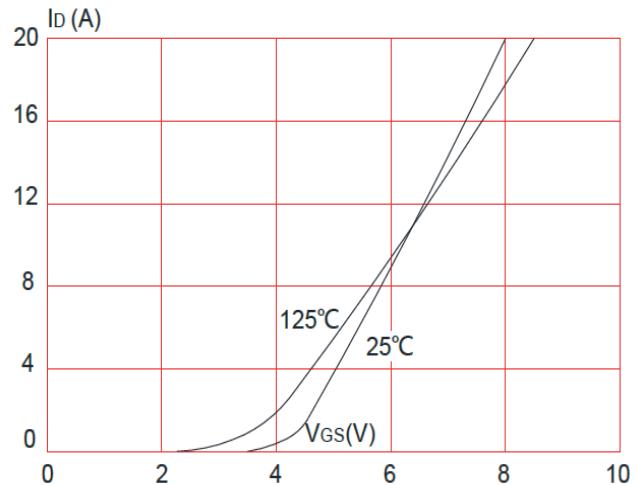
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$

### Typical Electrical and Thermal Characteristics (Curves)

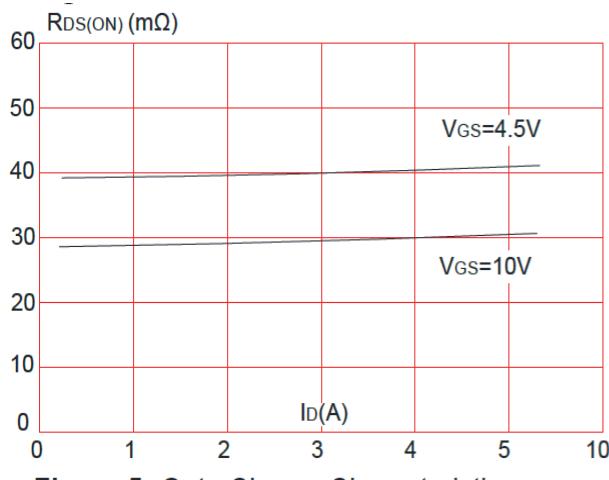
**Figure1: Output Characteristics**



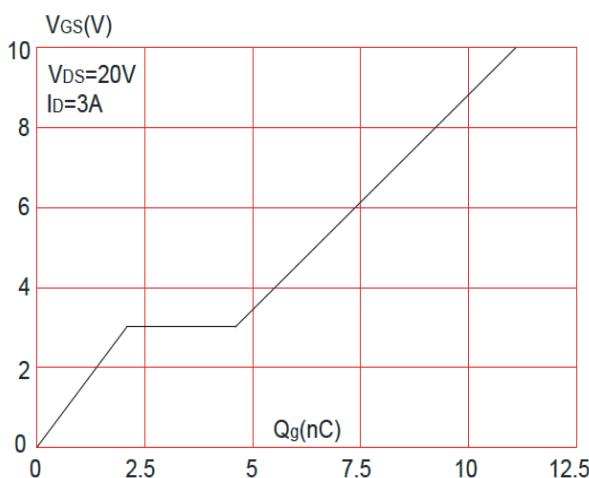
**Figure 2: Typical Transfer Characteristics**



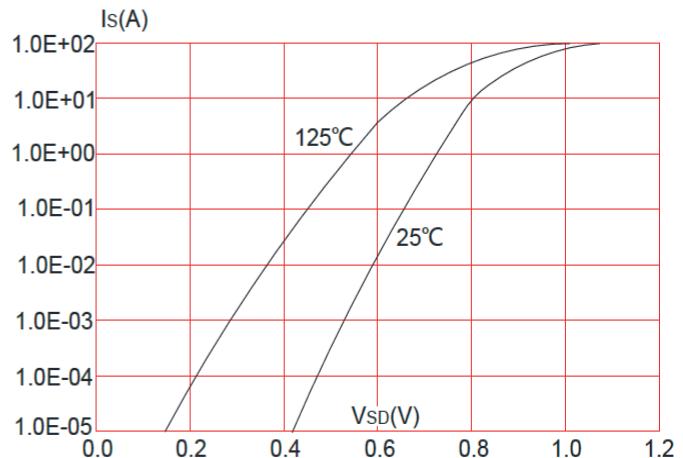
**Figure 3:On-resistance vs. Drain Current**



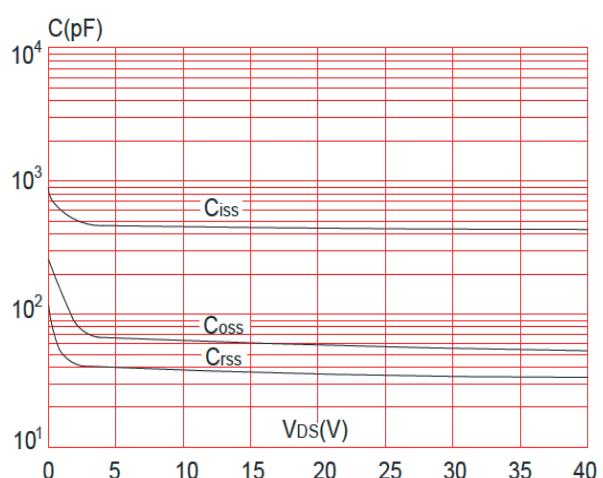
**Figure 5: Gate Charge Characteristics**



**Figure 4: Body Diode Characteristics**

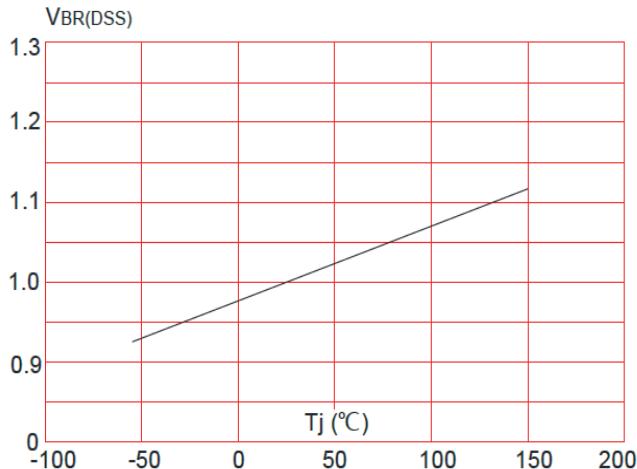


**Figure 6:Capacitance Characteristics**

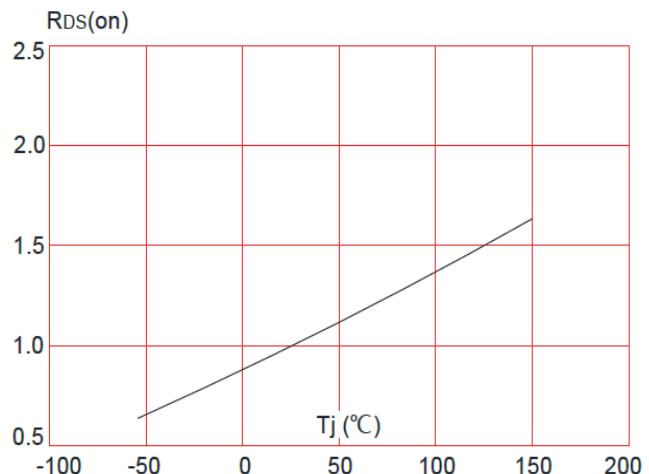


### Typical Performance Characteristics

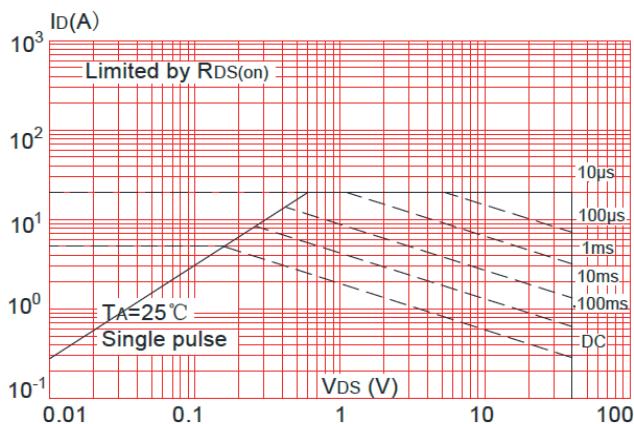
**Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**



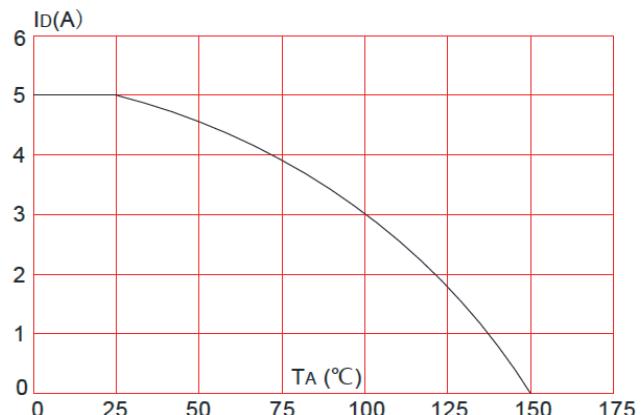
**Figure 8: Normalized on Resistance vs. Junction Temperature**



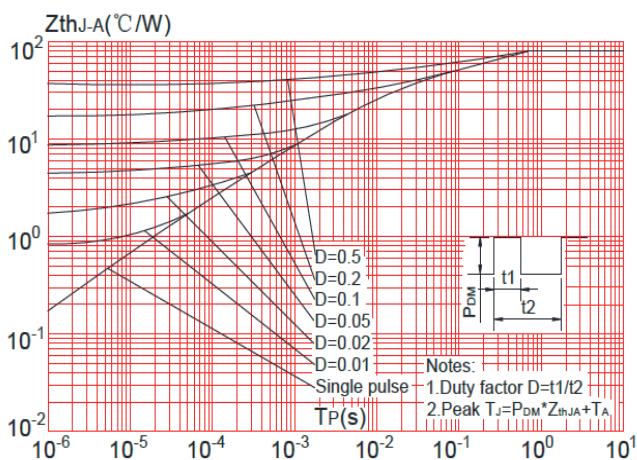
**Figure 9: Maximum Safe Operating Area**



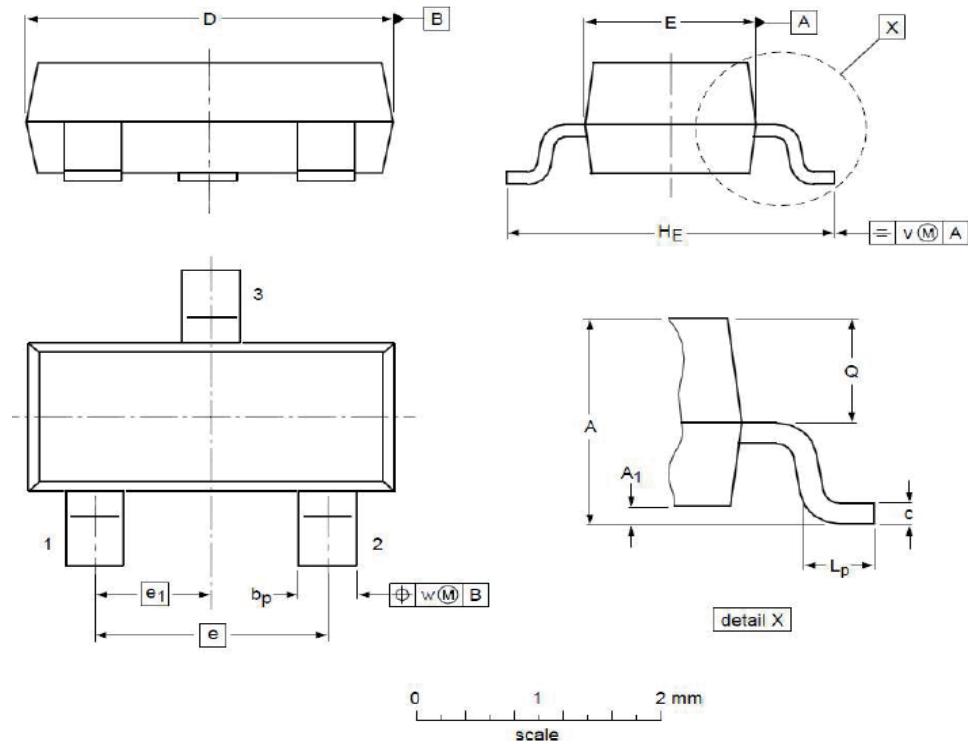
**Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature**



**Figure 11: Maximum Effective Transient Thermal Impedance vs. Duty Factor and Pulse Time**



## SOT23 Mechanical tData


**DIMENSIONS ( unit : mm )**

| Symbol               | Min  | Typ  | Max  | Symbol               | Min  | Typ  | Max  |
|----------------------|------|------|------|----------------------|------|------|------|
| <b>A</b>             | 0.90 | 1.01 | 1.15 | <b>A<sub>1</sub></b> | 0.01 | 0.05 | 0.10 |
| <b>b<sub>p</sub></b> | 0.30 | 0.42 | 0.50 | <b>c</b>             | 0.08 | 0.13 | 0.15 |
| <b>D</b>             | 2.80 | 2.92 | 3.00 | <b>E</b>             | 1.20 | 1.33 | 1.40 |
| <b>e</b>             | --   | 1.90 | --   | <b>e<sub>1</sub></b> | --   | 0.95 | --   |
| <b>H<sub>E</sub></b> | 2.25 | 2.40 | 2.55 | <b>L<sub>p</sub></b> | 0.30 | 0.42 | 0.50 |
| <b>Q</b>             | 0.45 | 0.49 | 0.55 | <b>v</b>             | --   | 0.20 | --   |
| <b>w</b>             | --   | 0.10 | --   |                      |      |      |      |